

PROTECTION PRODUCTS - Z-Pak™

Description

μ Clamp[®] TVS diodes are designed to protect sensitive electronics from damage or latch-up due to ESD. They are designed to replace 0201 size multilayer varistors (MLVs) in portable applications such as cell phones, notebook computers, and other portable electronics. They feature large cross-sectional area junctions for conducting high transient currents. These devices offer desirable characteristics for board level protection including fast response time, low operating and clamping voltage, and no device degradation.

μ Clamp[®]3311Z is constructed using Semtech's proprietary EPD process technology. The EPD process provides low standoff voltages with significant reductions in leakage currents and capacitance over silicon-avalanche diode processes. They feature a true operating voltage of 3.3 volts for superior protection when compared to traditional pn junction devices.

μ Clamp3311Z is in a 2-pin SLP0603P2X3A package. It measures 0.6 x 0.3 mm with a nominal height of only 0.25mm. Leads are finished with lead-free NiAu. Each device will protect one line operating at 3.3 volts. It gives the designer the flexibility to protect single lines in applications where arrays are not practical. The combination of small size and high ESD surge capability makes them ideal for use in portable applications such as cellular phones, digital cameras, and MP3 players.

Features

- ◆ High ESD withstand Voltage: **+/-14kV** (Contact) and **+/- 16kV** (Air) per **IEC 61000-4-2**
- ◆ Able to withstand over 1000 ESD strikes per IEC 61000-4-2 Level 4
- ◆ Ultra-small **0201 package**
- ◆ Protects one data line
- ◆ Low reverse current: <10nA typical (VR=5V)
- ◆ Working voltage: +/- 3.3V
- ◆ Low capacitance: 6pF typical
- ◆ Extremely low dynamic resistance: 0.21 Ohms (Typ)
- ◆ Solid-state silicon-avalanche technology

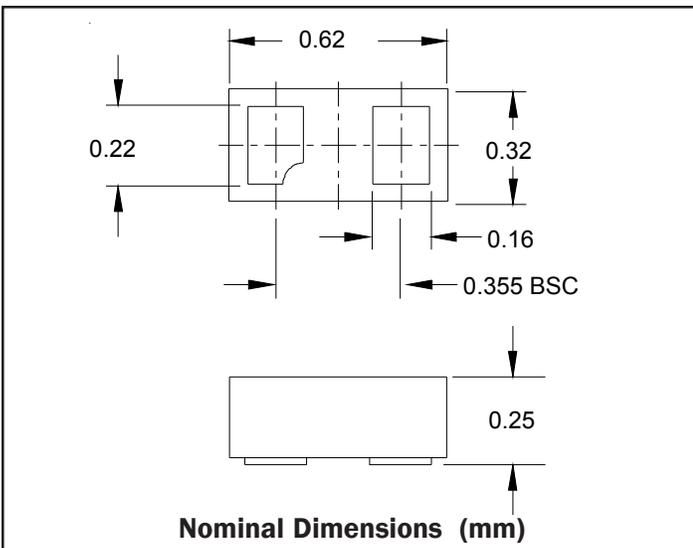
Mechanical Characteristics

- ◆ SLP0603P2X3A package
- ◆ Pb-Free, Halogen Free, RoHS/WEEE Compliant
- ◆ Nominal Dimensions: 0.6 x 0.3 x 0.25 mm
- ◆ Lead Finish: NiAu
- ◆ Marking : Marking code
- ◆ Packaging : Tape and Reel

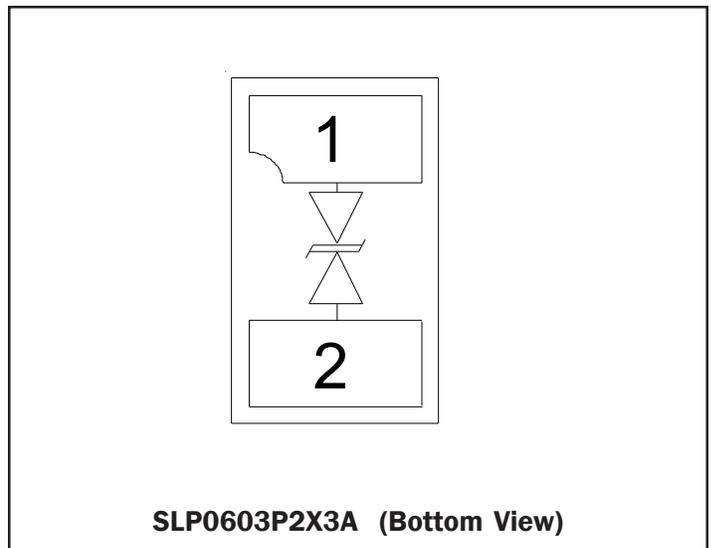
Applications

- ◆ Cellular Handsets & Accessories
- ◆ Keypads, Side Keys, Audio Ports
- ◆ Portable Instrumentation
- ◆ Digital Lines
- ◆ Tablet PC

Nominal Dimensions



Schematic



PROTECTION PRODUCTS

Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power (tp = 8/20μs)	P_{pk}	30	Watts
Maximum Peak Pulse Current (tp = 8/20μs)	I_{pp}	4	Amps
ESD per IEC 61000-4-2 (Air) ¹ ESD per IEC 61000-4-2 (Contact) ¹	V_{ESD}	+/- 16 +/- 14	kV
Operating Temperature	T_J	-40 to +85	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Characteristics (T=25°C)

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				3.3	V
Punch-Through Voltage	V_{PT}	$I_{PT} = 50\mu A$	3.65	4	4.4	V
Snap-Back Voltage	V_{SB}	$I_{SB} = 50mA$	2.8			V
Reverse Leakage Current	I_R	$V_{RWM} = 3.3V$		0.001	0.05	μA
Clamping Voltage	V_C	$I_{pp} = 1A, tp = 8/20\mu s$			5.5	V
Clamping Voltage	VC	$I_{pp} = 3A, tp = 8/20\mu s$			6.5	V
Clamping Voltage	V_C	$I_{pp} = 4A, tp = 8/20\mu s$			7.5	V
Dynamic Resistance ^{2, 3}	R_D	tp = 100ns		0.21		Ohms
Junction Capacitance	C_j	I/O pin to Gnd $V_R = 0V, f = 1MHz$		6	9	pF

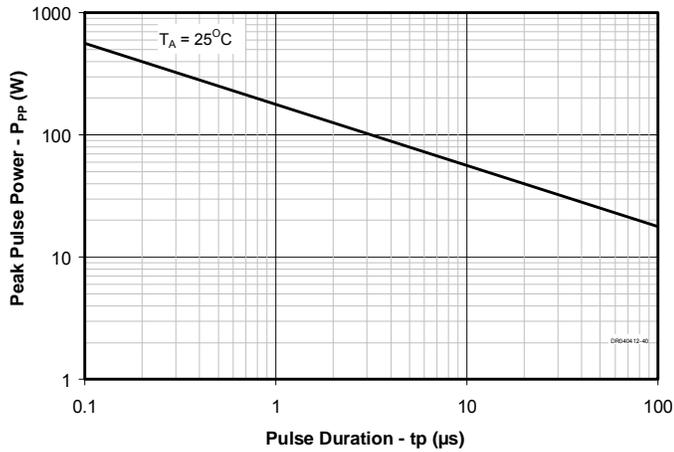
Notes

- 1)ESD gun return path connected to ESD ground reference plane.
- 2)Transmission Line Pulse Test (TLP) Settings: $t_p = 100ns, t_r = 0.2ns, I_{TLP}$ and V_{TLP} averaging window: $t_1 = 70ns$ to $t_2 = 90ns$.
- 3) Dynamic resistance calculated from $I_{TLP} = 4A$ to $I_{TLP} = 16A$

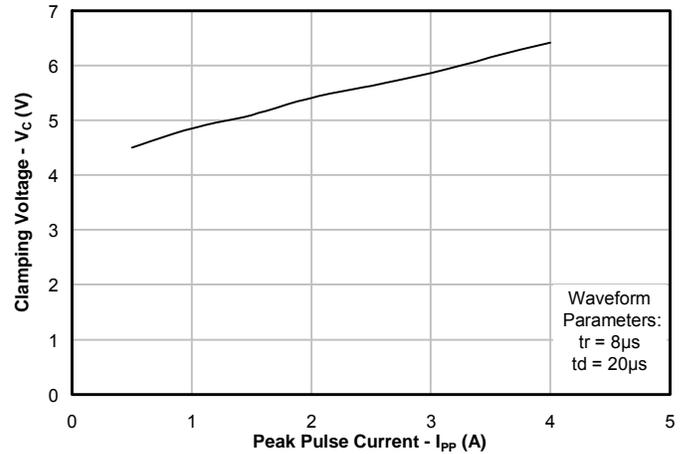
PROTECTION PRODUCTS

Typical Characteristics

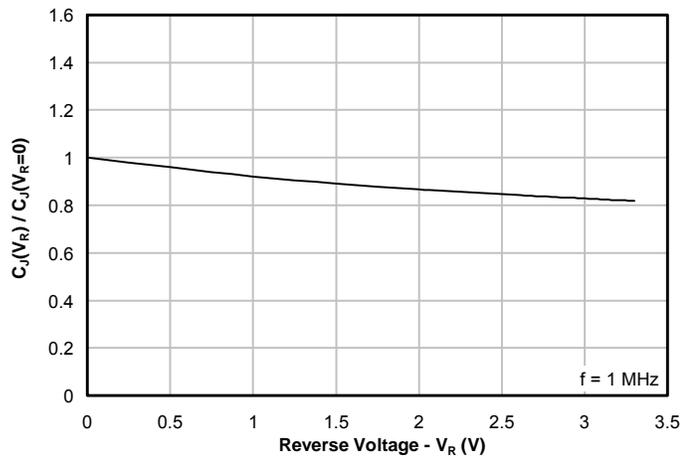
Non-Repetitive Peak Pulse Power vs. Pulse Time



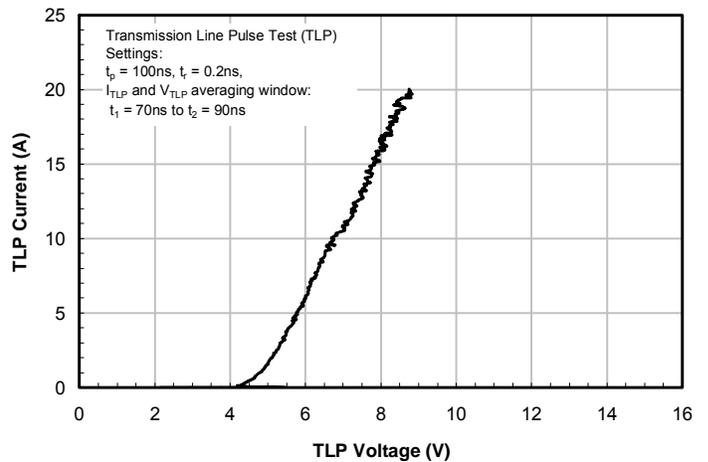
Clamping Voltage vs. Peak Pulse Current ($t_p=8/20\mu$ s)



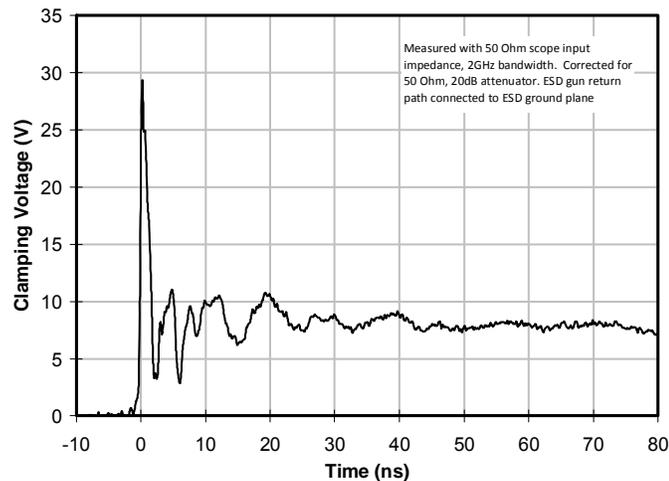
Normalized Junction Capacitance vs. Reverse Voltage



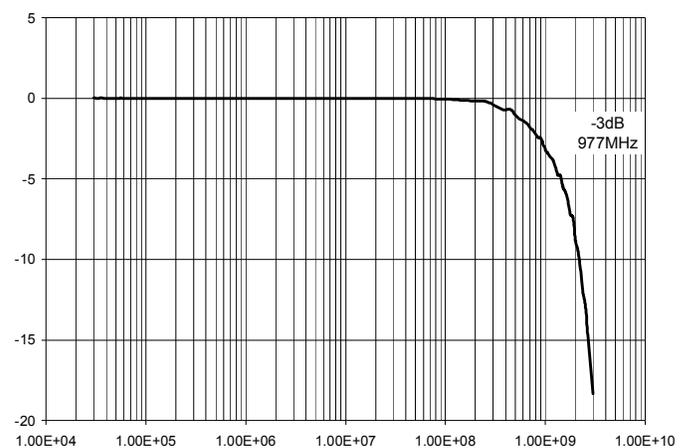
TLP Characteristic



ESD Clamping (+8kV Contact per IEC 61000-4-2)



**Typical Insertion Loss (S21)
30KHz to 3GHz**



PROTECTION PRODUCTS

Applications Information

Device Connection Options

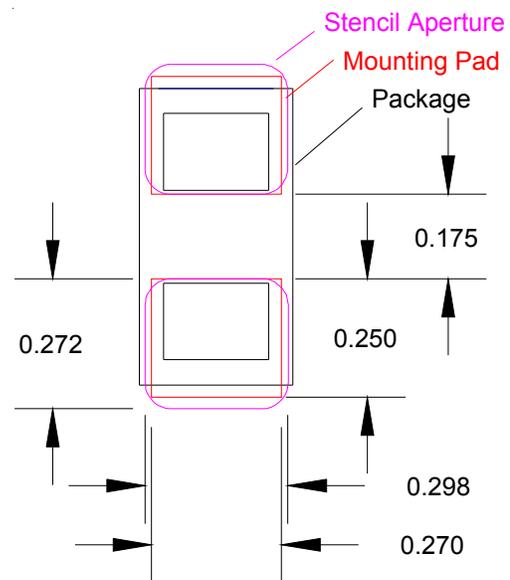
The μ Clamp3311Z is designed to protect one data line operating up to 3.3 volts. It will present a high impedance to the protected line up to 3.3 volts. It will “turn on” when the line voltage exceeds 3.5 volts. The device is bidirectional and may be used on lines where the signal polarity is above and below ground. These devices are not recommended for use on DC power supply lines due to their snap-back voltage characteristic.

Assembly Guidelines

The small size of this device means that some care must be taken during the mounting process to insure reliable solder joint. The table below provides Semtech's recommended assembly guidelines for mounting this device. The figure at the right details Semtech's recommended aperture based on the below recommendations. Note that these are only recommendations and should serve only as a starting point for design since there are many factors that affect the assembly process. The exact manufacturing parameters will require some experimentation to get the desired solder application.

Assembly Parameter	Recommendation
Solder Stencil Design	Laser cut, Electro-polished
Aperture shape	Rectangular with rounded corners
Solder Stencil Thickness	0.100 mm (0.004")
Solder Paste Type	Type 4 size sphere or smaller
Solder Reflow Profile	Per JEDEC J-STD-020
PCB Solder Pad Design	Non-Solder mask defined
PCB Pad Finish	OSP OR NiAu

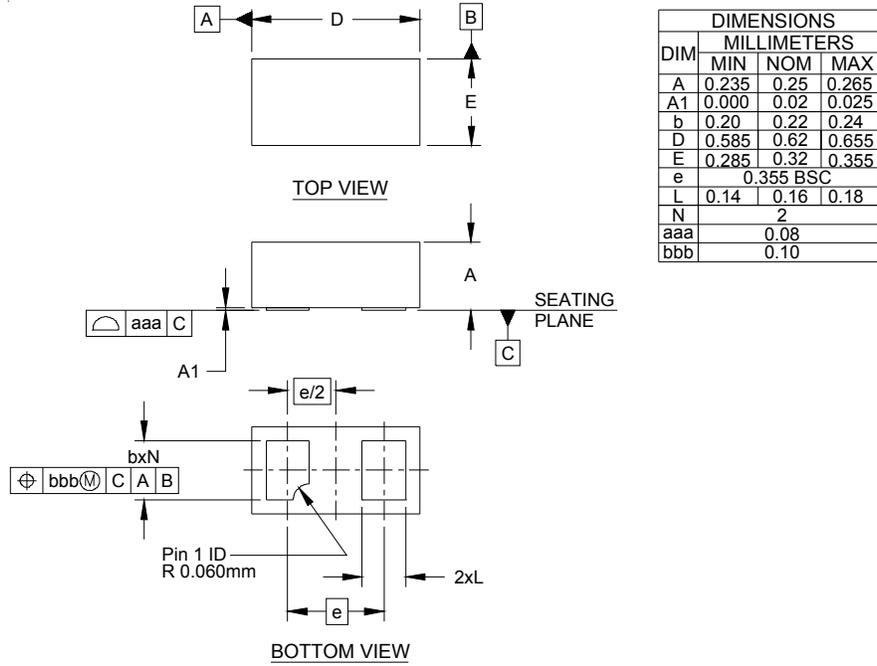
Circuit Diagram



Recommended Mounting Pattern

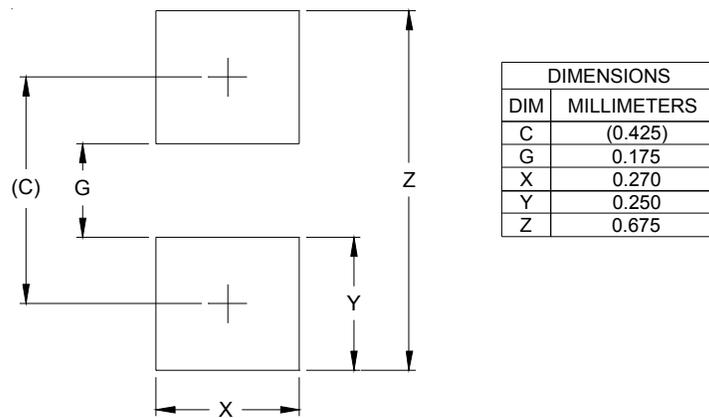
PROTECTION PRODUCTS

Outline Drawing - SLP0603P2X3A



NOTES:
 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).

Land Pattern - SLP0603P2X3A



NOTES:
 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY.
 CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR
 COMPANY'S MANUFACTURING GUIDELINES ARE MET.

PROTECTION PRODUCTS

Marking Code



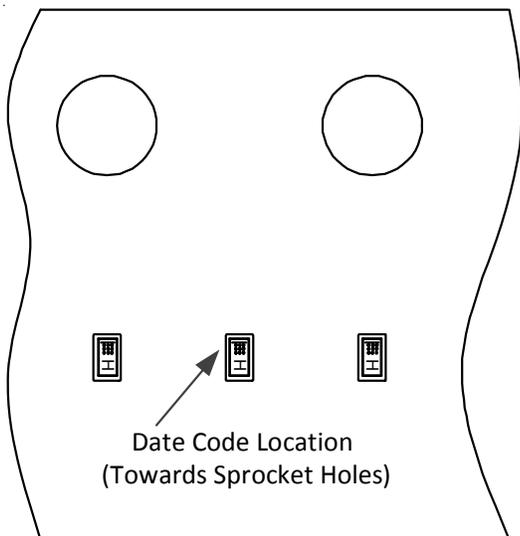
Notes:
 1) Dots represent date code matrix and Pin 1 location

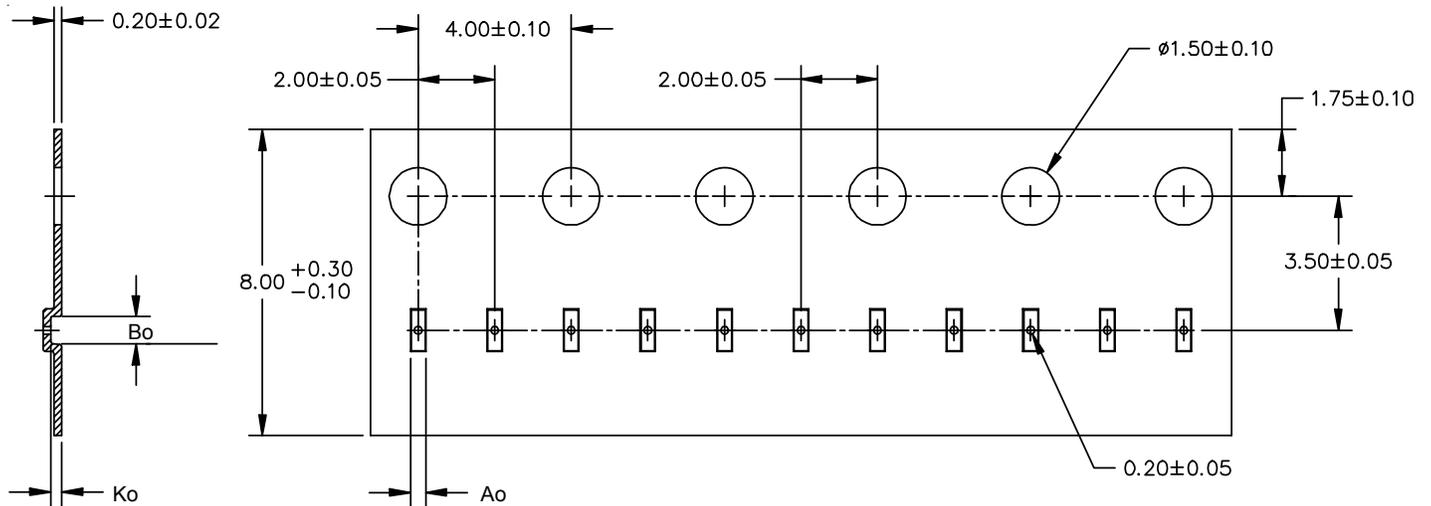
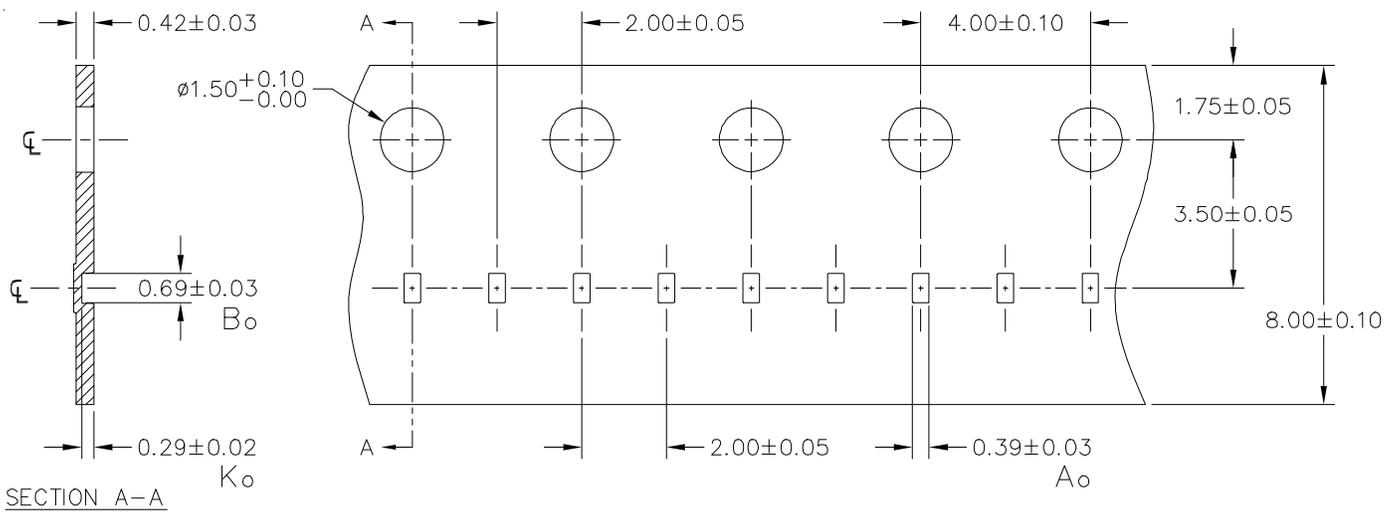
Ordering Information

Ordering Number	Qty per Reel	Carrier Tape	Reel Size	Comments
uClamp3311Z.TNT	10,000	Plastic	7 Inch	Not Recommended for New Designs
uClamp3311Z.TFT	15,000	Paper	7 Inch	
uClamp3311Z.TVT	50,000	Paper	13 Inch	

Notes:
 1) MicroClamp, uClamp and μ Clamp are trademarks of Semtech Corporation

Device Orientation in Tape



PROTECTION PRODUCTS
Carrier Tape Specification
Plastic Tape

Paper Tape


Note: All dimensions in mm unless otherwise specified

Contact Information

Semtech Corporation
Protection Products Division
200 Flynn Rd., Camarillo, CA 93012
Phone: (805)498-2111 FAX (805)498-3804



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.